

**Notice of References Cited**

Application/Control No.

09/763,891

Applicant(s)/Patent Under  
Reexamination  
UCHIDA ET AL.

Examiner

Lynette T. Umez-Eronini

Art Unit

1765

Page 1 of 1

**U.S. PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-4537654	08-1985	Berenz et al.	156/644
	B	US-4968381	11-1990	Prigge et al.	156/636
	C	US-5434107	07-1995	Paranjpe	437/225
	D	US-5691219	11-1997	Kawakubo et al.	437/52
	E	US-5770095	06-1998	Sasaki et al.	216/38
	F	US-5770103	06-1998	Wang et al.	252/79.1
	G	US-5876490	03-1999	Ronay	106/3
	H	US-5932486	08-1999	Cook et al.	438/692
	I	US-5954997	09-1999	Kaufman et al.	252/79.1
	J	US-5981394	11-1999	Ohashi et al.	438/692
	K	US-			
	L	US-			
	M	US-			

**FOREIGN PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	O					
	P					
	Q					
	R					
	S					
	T					

**NON-PATENT DOCUMENTS**

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Hayashi, Y. et al., "A New Abrasive-Free, Chemical-Mechanical-Polishing for Aluminium Metallization of ULSI Devices, International Electron Devices Meeting Technical Digest, 1992, pp. 976-978.
	V	
	W	
	X	

\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.